

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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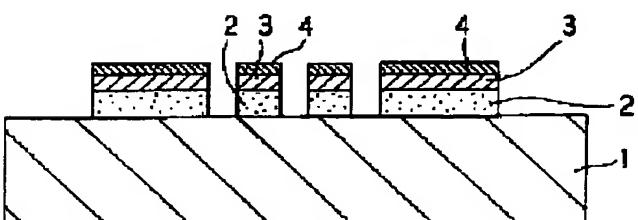
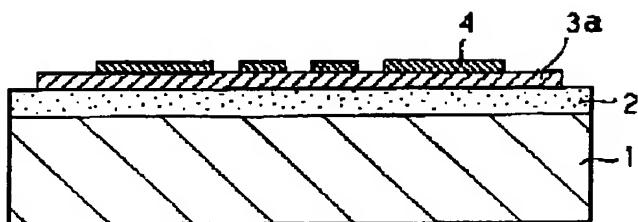
APPLICATION DATE : 27-07-92  
APPLICATION NUMBER : 04199782

APPLICANT : SONY CORP;

INVENTOR : KOMATSU NOBUO;

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TITLE : MANUFACTURE OF PRINTED WIRING BOARD



ABSTRACT : PURPOSE: To realize a manufacturing method for printed wiring boards by which mass productivity equal to that of prior art screen process printing can be obtained along with making resist patterns much thinner and more accurate.

CONSTITUTION: A first resist layer 3a, alkalescent ( $9 \leq \text{pH} < 13$ ) and soluble, is formed over the whole surface of a copper foil 2 clad on an insulating board 1. After a second pattern resist 4 of a specified pattern being a strong base ( $\text{pH} \geq 13$ ) and soluble is formed on the first resist layer 3a, a first pattern resist 3 is formed by developing the first resist layer 3a with an alkalescent solution using the second pattern resist 4 as a make. The copper foil 2 is etched using these first and second pattern resists 3 and 4 as masks, and a wiring pattern having a specified pattern is formed by removing the first and second pattern resists with a strong base solution.

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